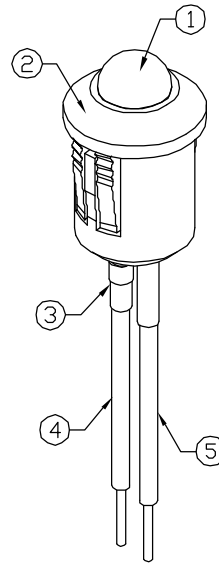
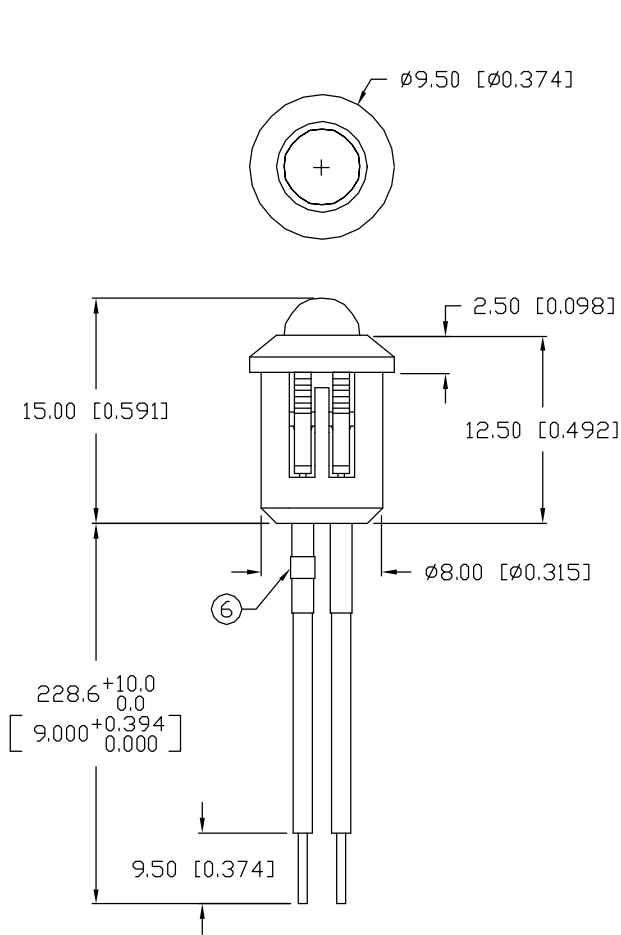
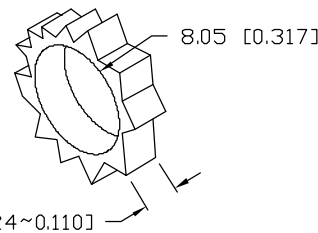


PRELIMINARY IN P/N DIR

CAUTION: PRESSURE SENSITIVE ASSEMBLY  
AVOID APPLYING PRESSURE TO LED  
DURING PANEL ASSEMBLY.



PANEL CUTOUT



ELECTRO-OPTICAL CHARACTERISTICS		T <sub>A</sub> =25°C		V <sub>f</sub> =28V	
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		WHITE		nm	
FORWARD VOLTAGE		28		V <sub>f</sub>	
REVERSE VOLTAGE	5.0			V <sub>r</sub>	I <sub>r</sub> =100μA
AXIAL INTENSITY		200		mcd	V <sub>f</sub> =28V
VIEWING ANGLE		34		2x theta	
EMITTED COLOR:	WHITE				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER DIE		
PARAMETER	MAX	UNITS
PEAK FORWARD VOLTAGE	29.5	V
STEADY CURRENT	18	mA
POWER DISSIPATION	500	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

NOTES:

1. SSL-LX5093UW, WHITE LED. TRIM LEADS TO 5mm.
2. SSH-RTF5010, BLACK HOLDER.
3. LXP-HEATSHRINK-3, (2 PCS.) 1/8" x 50mm.
4. ANODE LEAD: LXP-WST24RDT0C, CUT 180mm LONG, STRIP ENDS 3mm & 9.5mm.
5. CATHODE LEAD: LXP-WST24BLT0C, CUT 210mm LONG, STRIP ENDS 3mm & 9.5mm.
6. LXP-RES 2700 1/2W, CUT 22-24mm.



UNCONTROLLED DOCUMENT

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION MAX.=+0.00 -DECIMAL PRECISION

REV.	PART NUMBER
	SSI-LXR5010UW41249

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T-5mm, ULTRA WHITE LED PANEL INDICATOR,  
WHITE DIFFUSED LENS, 9" WIRE LEADS, 28 VOLTS.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JN	CHECKED BY:	APPROVED BY:	DATE: 09.04.08
			PAGE: 1 OF 1
			SCALE: N/A